



Material Content Data Sheet



Sales Product Name		ESD206-B1-02EL E6327		Issued		25. September 2017		
MA#		MA001124098						
Package		PG-TSLP-2-19		Weight*		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.06		575	
	noble metal	gold	7440-57-5	0.001	0.22		2228	
	inorganic material	silicon	7440-21-3	0.010	1.65	1.93	16511	19314
leadframe	non noble metal	nickel	7440-02-0	0.241	39.64	39.64	396362	396362
wire	non noble metal	copper	7440-50-8	0.003	0.43	0.43	4256	4256
encapsulation	organic material	carbon black	1333-86-4	0.002	0.27		2702	
	plastics	epoxy resin	-	0.048	7.84		78358	
	inorganic material	silicondioxide	60676-86-0	0.279	45.92	54.03	459344	540404
leadfinish	noble metal	gold	7440-57-5	0.010	1.72	1.72	17163	17163
plating	noble metal	palladium	7440-05-3	0.003	0.53		5338	
	noble metal	gold	7440-57-5	0.010	1.72	2.25	17163	22501
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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